



## 8-Channel, 12-Bit, 65MSPS ADC with Serial LVDS Interface

### FEATURES

- Maximum Sample Rate: 65MSPS
- 12-Bit Resolution
- No Missing Codes
- Power Dissipation: 996mW
- CMOS Technology
- Simultaneous Sample-and-Hold
- 70.5dB SNR at 10MHz IF
- Internal and External References
- 3.3V Digital/Analog Supply
- Serialized LVDS Outputs
- Integrated Frame and Synch Patterns
- MSB and LSB First Modes
- Option to Double LVDS Clock Output Currents
- Pin- and Format-Compatible Family
- TQFP-80 PowerPAD™ Package

### APPLICATIONS

- Portable Ultrasound Systems
- Tape Drives
- Test Equipment
- Optical Networking

### DESCRIPTION

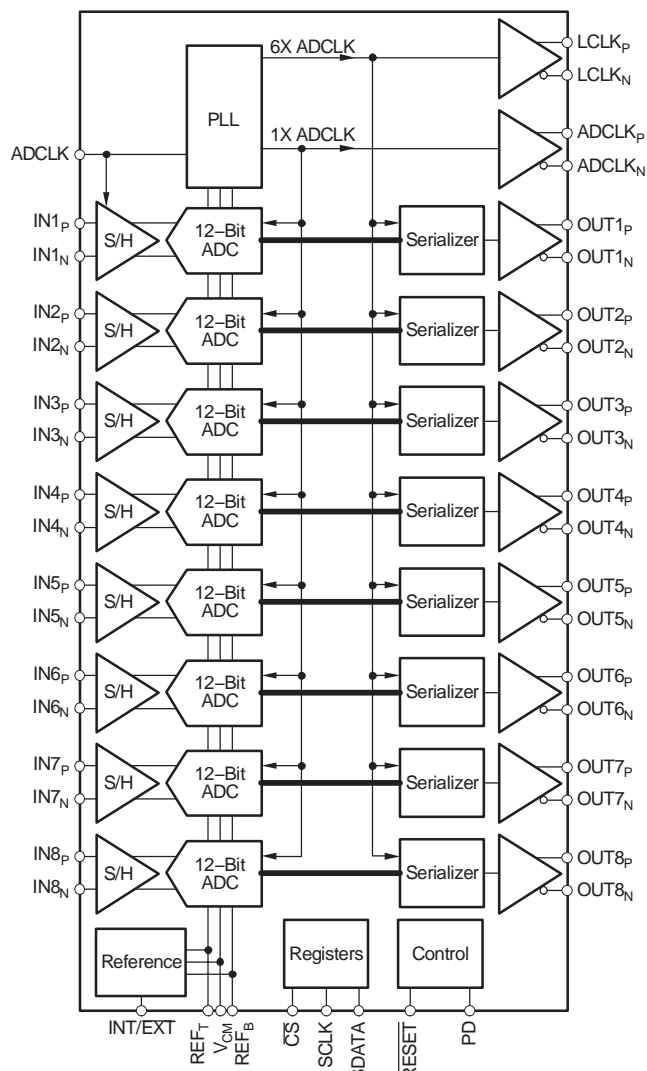
The ADS5272 is a high-performance, 65MSPS, 8-channel, parallel analog-to-digital converter (ADC). Internal references are provided, simplifying system design requirements. Low power consumption allows for the highest of system integration densities. Serial LVDS (low-voltage differential signaling) outputs reduce the number of interface lines and package size.

An integrated phase lock loop multiplies the incoming ADC sampling clock by a factor of 12. This 12x clock is used in the process of serializing the data output from each channel. The 12x clock is also used to generate a 1x and a 6x clock, both of which are transmitted as LVDS clock outputs. The 6x clock is denoted by the differential pair LCLKP and LCLKN, while the 1x clock is denoted by ADCLKP and ADCLKN. The word output of each ADC channel can be transmitted either as MSB

or LSB first. The bit coinciding with the rising edge of the 1x clock output is the first bit of the word. Data is to be latched by the receiver on both the rising and falling edges of the 6x clock.

The ADS5272 provides internal references, or can optionally be driven with external references. Best performance can be achieved through the internal reference mode.

The device is available in a TQFP-80 PowerPAD package and is specified over a  $-40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$  operating range.



PRODUCT PREVIEW



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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**ABSOLUTE MAXIMUM RATINGS(1)**

Supply Voltage Range, AVDD	-0.3V to 3.8V
Supply Voltage Range, LVDD	-0.3V to 3.8V
Voltage Between AVSS and LVSS	-0.3V to 0.3V
Voltage Between AVDD and LVDD	-0.3V to 0.3V
Voltages Applied to External REF Pins	-0.3V to 2.4V
All LVDS Data and Clock Outputs	-0.3V to 2.4V
Analog Input Pins	-0.3V to 2.7V
Peak Total Input Current (all inputs)	-30mA
Operating Free-Air Temperature Range, T <sub>A</sub>	-40°C to 85°C
Lead Temperature 1.6mm (1/16" from case for 10s)	220°C



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

(1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not supported.

**ORDERING INFORMATION(1)**

PRODUCT	PACKAGE-LEAD	PACKAGE DESIGNATOR	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER	TRANSPORT MEDIA, QUANTITY
ADS5272	HTQFP-80(2)	PFP	-40°C to +85°C	ADS5272IPFP	ADS5272IPFP ADS5272IPFPT	Tray, 96 Tape and Reel, 250

(1) For the most current package and ordering information, see the Package Option Addendum located at the end of this data sheet.  
 (2) Thermal pad size: 4.69mm x 4.69mm (min), 6.20mm x 6.20mm (max).

**RELATED PRODUCTS**

MODEL	RESOLUTION (BITS)	SAMPLE RATE (MSPS)	CHANNELS
ADS5270	12	40	8
ADS5271	12	50	8
ADS5273	12	70	8
ADS5275	10	40	8
ADS5276	10	50	8
ADS5277	10	65	8

**RECOMMENDED OPERATING CONDITIONS**

	ADS5272			UNIT
	MIN	TYP	MAX	
<b>SUPPLIES AND REFERENCES</b>				
Analog Supply Voltage, AVDD	3.0	3.3	3.6	V
Output Driver Supply Voltage, LVDD	3.0	3.3	3.6	V
<b>CLOCK INPUT AND OUTPUTS</b>				
ADCLK Input Sample Rate (low-voltage TTL)	20		65	MSPS
Low Level Voltage Clock Input			0.6	V
High Level Voltage Clock Input				V
ADCLK <sub>P</sub> and ADCLK <sub>N</sub> Outputs (LVDS)	20		65	MHz
LCLK <sub>P</sub> and LCLK <sub>N</sub> Outputs (LVDS)(1)	120		390	MHz
Operating Free-Air Temperature, T <sub>A</sub>	-40		+85	°C
<b>Thermal Characteristics</b>				
θ <sub>JA</sub>		21		°C/W
θ <sub>JC</sub>		68		°C/W

(1) 6 × ADCLK.

**REFERENCE SELECTION**

MODE	INT/EXT	DESCRIPTION
2.0V <sub>pp</sub> Internal Reference	1	Default with internal pull-up.
External Reference	0	Internal reference is powered down. Common mode of external reference should be within 50mV of V <sub>CM</sub> . V <sub>CM</sub> is derived from the internal bandgap voltage.

PRODUCT PREVIEW

## ELECTRICAL CHARACTERISTICS

$T_{MIN} = -40^{\circ}C$ , and  $T_{MAX} = +85^{\circ}C$ . Typical values are at  $T_A = 25^{\circ}C$ , clock frequency = maximum specified, 50% clock duty cycle,  $AVDD = 3.3V$ ,  $LVDD = 3.3V$ , -1dBFS, internal voltage reference, and LVDS buffer current at 3.5mA per channel, unless otherwise noted.

PARAMETER	TEST CONDITIONS	ADS5272			UNITS
		MIN	TYP	MAX	
<b>DC ACCURACY</b>					
No Missing Codes			Assured		
DNL Differential Nonlinearity	$f_{IN} = 5MHz$	-0.9	$\pm 0.5$	0.9	LSB
INL Integral Nonlinearity	$f_{IN} = 5MHz$	-2.0	$\pm 0.6$	2.0	LSB
Offset Error <sup>(1)</sup>		TBD	$\pm 0.2$	TBD	%FS
Offset Temperature Coefficient			14		ppm/ $^{\circ}C$
Fixed Attenuation in Channel <sup>(2)</sup>			1		%FS
Variable Attenuation in Channel <sup>(3)</sup>			$\pm 0.2$		%FS
Gain Error <sup>(4)</sup>	$REF_T - REF_B$	TBD	$\pm 1.0$	TBD	%FS
Gain Temperature Coefficient <sup>(5)</sup>			44		ppm/ $^{\circ}C$
<b>POWER SUPPLY</b>					
$I_{CC}$ Total Supply Current	$V_{IN} = FS, F_{IN} = 5MHz$		302		mA
$I(AVDD)$ Analog Supply Current	$V_{IN} = FS, F_{IN} = 5MHz$		TBD		mA
$I(LVDD)$ Digital Output Driver Supply Current	$V_{IN} = FS, F_{IN} = 5MHz, LVDS$ Into 100 $\Omega$ Load		TBD		mA
Power Dissipation			996	TBD	mW
Power Down	Clock Running		90		mW
<b>REFERENCE VOLTAGES</b>					
$V_{REF_T}$ Reference Top (internal)		1.95	2.0	2.05	V
$V_{REF_B}$ Reference Bottom (internal)		0.95	1.0	1.05	V
$V_{CM}$ Common-Mode Voltage		1.45	1.5	1.55	V
$V_{CM}$ Output Current <sup>(6)</sup>	$\pm 50mV$ Change in Voltage		$\pm 2$		mA
$V_{REF_T}$ Reference Top (external)		1.875			V
$V_{REF_B}$ Reference Bottom (external)				1.125	V
External Reference Input Current <sup>(7)</sup>			2.0		mA
<b>ANALOG INPUT</b>					
Differential Input Capacitance			7.0		pF
Analog Input Common-Mode Range				$V_{CM} \pm 0.05$	V
Differential Input Voltage Range		1.5		2.02	$V_{PP}$
Voltage Overload Recovery Time	Differential Input Signal at 4 $V_{PP}$ Recovery to Within 1% of Code		4.0		CLK Cycles
Input Bandwidth	-3dBFS		300		MHz
<b>DIGITAL DATA OUTPUTS</b>					
Data Bit Rate		340		780	MBPS
<b>SERIAL INTERFACE</b>					
SCLK Serial Clock Input Frequency				20	MHz
$V_{IN LOW}$ Input Low Voltage		0		0.6	V
$V_{IN HIGH}$ Input High Voltage		2.1		VDD	V
Input Current			$\pm 10$		$\mu A$
Input Pin Capacitance			5.0		pF

(1) Offset error is the deviation of the average code from mid-code for a zero input. Offset error is expressed in terms of % of full-scale.

(2) Fixed attenuation in the channel arises due to a fixed attenuation of about 1% in the sample-and-hold amplifier. When the differential voltage at the analog input pins are changed from  $-V_{REF}$  to  $+V_{REF}$ , the swing of the output code is expected to deviate from the full-scale code (4096LSB) by the extent of this fixed attenuation [ $V_{REF}$  is defined as  $(REF_T - REF_B)$ ].

(3) Variable attenuation in the channel refers to the attenuation of the signal in the channel over and above the fixed attenuation.

(4) The reference voltages are trimmed at production so that  $(V_{REF_T} - V_{REF_B})$  is within  $\pm 25mV$  of the ideal value of 1V. It does not include fixed attenuation.

(5) The gain temperature coefficient refers to the temperature coefficient of the attenuation in the channel. It does not account for the variation of the reference voltages with temperature.

(6)  $V_{CM}$  provides the common-mode current for the inputs of all eight channels when the inputs are AC-coupled. The  $V_{CM}$  output current specified is the additional drive of the  $V_{CM}$  buffer if loaded externally.

(7) Average current drawn from the reference pins in the external reference mode.

### AC CHARACTERISTICS

T<sub>MIN</sub> = -40°C, T<sub>MAX</sub> = +85°C. Typical values are at T<sub>A</sub> = 25°C, clock frequency = maximum specified, 50% clock duty cycle, AVDD = 3.3V, LVDD = 3.3V, -1dBFS, internal voltage reference, and LVDS buffer current at 3.5mA per channel, unless otherwise noted.

PARAMETER	CONDITIONS	ADS5272			UNITS
		MIN	TYP	MAX	
<b>DYNAMIC CHARACTERISTICS</b>					
SFDR Spurious-Free Dynamic Range	f <sub>IN</sub> = 1MHz	TBD	87		dBc
	f <sub>IN</sub> = 5MHz		85		dBc
	f <sub>IN</sub> = 10MHz		85		dBc
	f <sub>IN</sub> = 20MHz		83		dBc
HD <sub>2</sub> 2nd-Order Harmonic Distortion	f <sub>IN</sub> = 1MHz	TBD	90		dBc
	f <sub>IN</sub> = 5MHz		90		dBc
	f <sub>IN</sub> = 10MHz		89		dBc
	f <sub>IN</sub> = 20MHz		86		dBc
HD <sub>3</sub> 3rd-Order Harmonic Distortion	f <sub>IN</sub> = 1MHz	TBD	87		dBc
	f <sub>IN</sub> = 5MHz		85		dBc
	f <sub>IN</sub> = 10MHz		85		dBc
	f <sub>IN</sub> = 20MHz		83		dBc
SNR Signal-to-Noise Ratio	f <sub>IN</sub> = 1MHz	TBD	70.5		dBFS
	f <sub>IN</sub> = 5MHz		70.5		dBFS
	f <sub>IN</sub> = 10MHz		70.5		dBFS
	f <sub>IN</sub> = 20MHz		70.5		dBFS
SINAD Signal-to-Noise and Distortion	f <sub>IN</sub> = 1MHz	TBD	70		dBFS
	f <sub>IN</sub> = 5MHz		70		dBFS
	f <sub>IN</sub> = 10MHz		70		dBFS
	f <sub>IN</sub> = 20MHz		70		dBFS
IMD Two-Tone Intermodulation Distortion	f <sub>1</sub> = 9.5MHz at -7dBFS		-85		dBFS
	f <sub>2</sub> = 10.2MHz at -7dBFS				
ENOB Effective Number of Bits	f <sub>IN</sub> = 5MHz		11.3		Bits
Crosstalk	Signal Applied to 7 Channels; Measurement Taken on the Channel with No Input Signal		-90		dBc

### LVDS DIGITAL DATA AND CLOCK OUTPUTS

Test conditions at I<sub>O</sub> = 3.5mA, R<sub>LOAD</sub> = 100Ω, and C<sub>LOAD</sub> = 9pF. I<sub>O</sub> refers to the current setting for the LVDS buffer. R<sub>LOAD</sub> is the differential load resistance between the differential LVDS pair. C<sub>LOAD</sub> is the effective single-ended load capacitance between the differential LVDS pins and ground. C<sub>LOAD</sub> includes the receiver input parasitics as well as the routing parasitics. Measurements are done with a transmission line of 100Ω differential impedance between the device and the load. All LVDS specifications are functionally tested, but not parametrically tested.

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
<b>DC SPECIFICATIONS<sup>(1)</sup></b>					
V <sub>OH</sub> Output Voltage High, OUT <sub>P</sub> or OUT <sub>N</sub>	R <sub>LOAD</sub> = 100Ω ± 1%; See LVDS Timing Diagram, Page 7		1375	1500	mV
V <sub>OL</sub> Output Voltage Low, OUT <sub>P</sub> or OUT <sub>N</sub>	R <sub>LOAD</sub> = 100Ω ± 1%	900	1025		mV
V <sub>OD</sub>   Output Differential Voltage,  OUT <sub>P</sub> - OUT <sub>N</sub>	R <sub>LOAD</sub> = 100Ω ± 1%	300	350	400	mV
V <sub>OS</sub> Output Offset Voltage <sup>(2)</sup>	R <sub>LOAD</sub> = 100Ω ± 1%; See LVDS Timing Diagram, Page 7	1100	1200	1300	mV
C <sub>O</sub> Output Capacitance <sup>(3)</sup>	V <sub>CM</sub> = 1.5V		4		pF
ΔV <sub>OD</sub>   Change in  V <sub>OD</sub>   Between 0 and 1	R <sub>LOAD</sub> = 100Ω ± 1%			25	mV
ΔV <sub>OS</sub> Change Between 0 and 1	R <sub>LOAD</sub> = 100Ω ± 1%			25	mV
ISOUT Output Short-Circuit Current	Drivers Shorted to Ground			40	mA
ISOUT <sub>NP</sub> Output Current	Drivers Shorted Together			12	mA
<b>DRIVER AC SPECIFICATIONS</b>					
Clock Clock Signal Duty Cycle	6 × ADCLK	45	50	55	%
			650		ps
			650		ps
t <sub>RISE</sub> /t <sub>FALL</sub> V <sub>OD</sub> Rise Time or V <sub>OD</sub> Fall Time	I <sub>O</sub> = 2.5mA		400		ps
	I <sub>O</sub> = 3.5mA		250		ps
	I <sub>O</sub> = 4.5mA		200		ps
	I <sub>O</sub> = 6mA		150		ps

- (1) The DC specifications refer to the condition where the LVDS outputs are not switching, but are permanently at a valid logic level 0 or 1.
- (2) V<sub>OS</sub> refers to the common-mode of OUT<sub>P</sub> and OUT<sub>N</sub>.
- (3) Output capacitance inside the device, from either OUT<sub>P</sub> or OUT<sub>N</sub> to ground.
- (4) Refer to the LVDS application note (SBAA118) for a description of data setup and hold times.
- (5) Setup and hold time specifications take into account the effect of jitter on the output data and clock. These specifications also assume that the data and clock paths are perfectly matched within the receiver. Any mismatch in these paths within the receiver would appear as reduced timing margins.

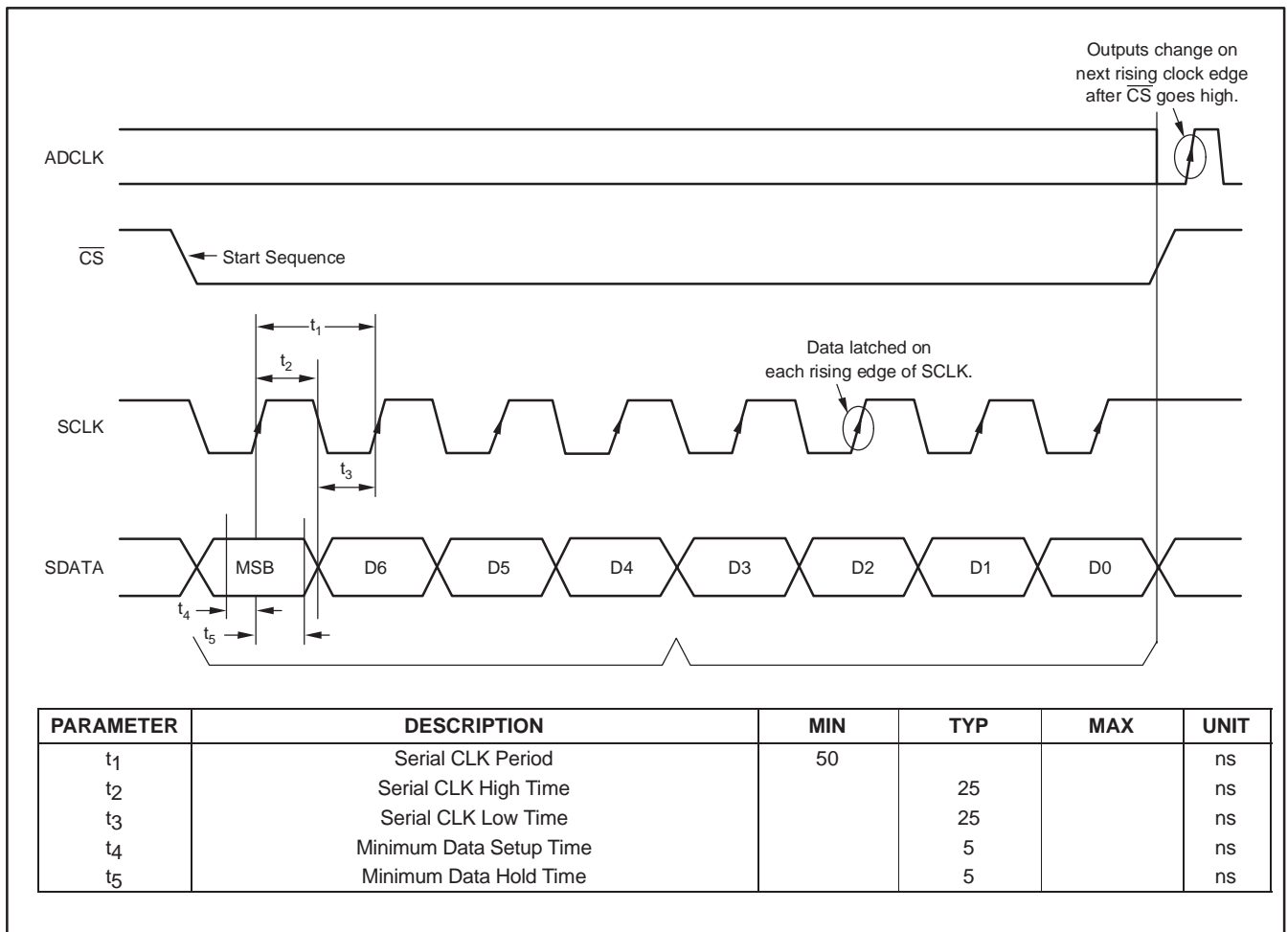
## SWITCHING CHARACTERISTICS

$T_{MIN} = -40^{\circ}C$ ,  $T_{MAX} = +85^{\circ}C$ . Typical values are at  $T_A = 25^{\circ}C$ , clock frequency = maximum specified, 50% clock duty cycle,  $AVDD = 3.3V$ ,  $LVDD = 3.3V$ , -1dBFS, internal voltage reference, and LVDS buffer current at 3.5mA per channel, unless otherwise noted.

PARAMETER	CONDITIONS	ADS5272			UNITS
		MIN	TYP	MAX	
<b>SWITCHING SPECIFICATIONS</b>					
$t_{SAMPLE}$		25		50	ns
$t_D(A)$ Aperture Delay			2.5		ns
Aperture Jitter (uncertainty)			1		ps
$t_D(\text{pipeline})$ Latency			6.5		cycles
$t_{PROP}$ Propagation Delay			5		ns

## SERIAL INTERFACE TIMING

Data is shifted in MSB first.



**SERIAL INTERFACE TIMING**

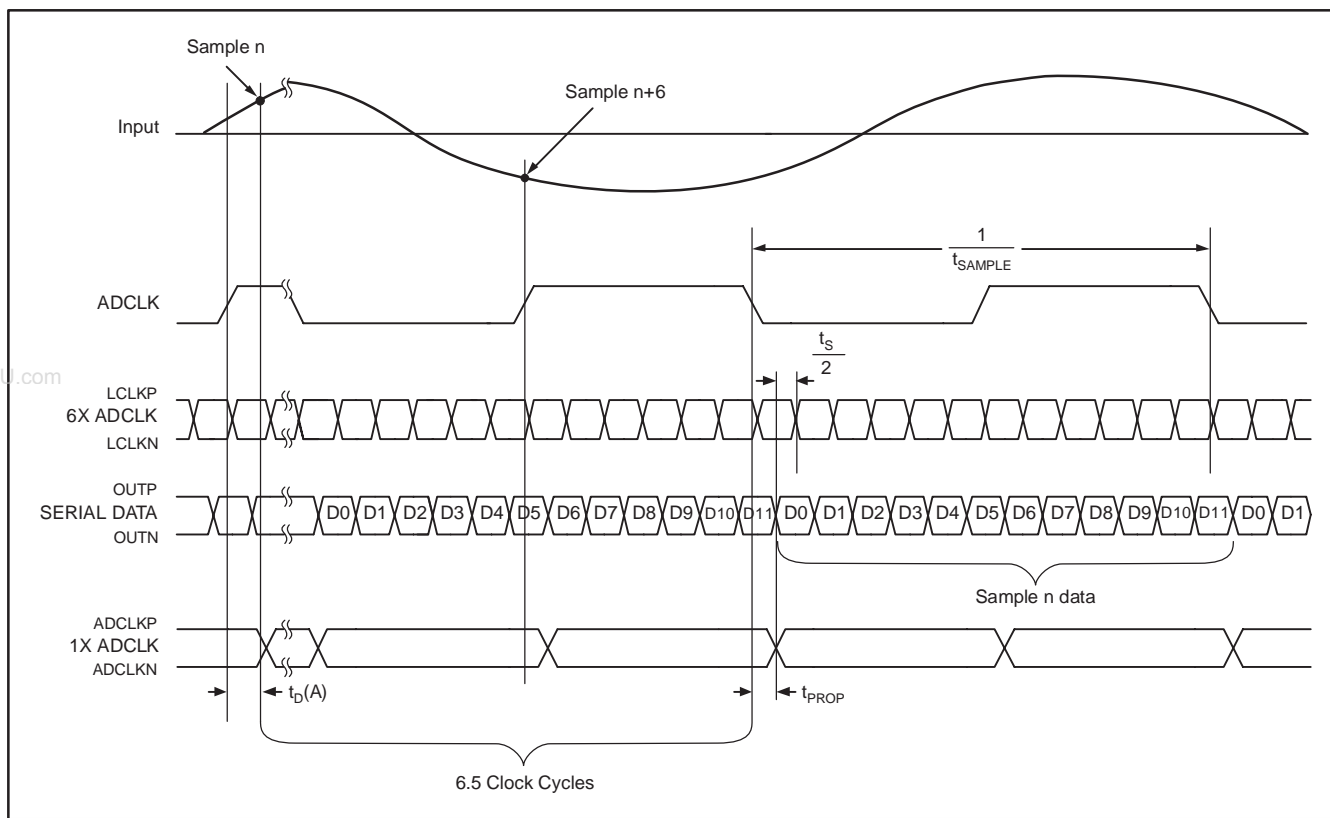
ADDRESS				DATA				DESCRIPTION	REMARKS
D7	D6	D5	D4	D3	D2	D1	D0		
0	0	0	0	0	0			<b>0. LVDS BUFFERS</b> Normal ADC Output Deskew Pattern Sync Pattern Custom Pattern Output Current in LVDS = 3.5mA Output Current in LVDS = 2.5mA Output Current in LVDS = 4.5mA Output Current in LVDS = 6.0mA	Patterns Get Reversed in MSB First Mode of LVDS
				0	1				
				1	0		0		
				1	1		0		
							1		
0	0	0	1	<b>D3</b>	<b>D2</b>	<b>D1</b>	<b>D0</b>	<b>1. LSB/MSB MODE</b> Default LVDS Clock Output Current 2X LVDS Clock Output Current LSB Mode MSB Mode	
				0	X	X	1		
				0	0	X	X		
				0	1	X	X		
0	0	1	0	<b>D3</b>	<b>D2</b>	<b>D1</b>	<b>D0</b>	<b>2. POWER-DOWN ADC CHANNELS</b>  Power-Down Channels 1 to 4; D3 is for Channel 4 and D0 for Channel 1	Example: 1010 Powers Down Channels 4 and 2 and Keeps Channels 1 and 3 Alive
				X	X	X	X		
0	0	1	1	<b>D3</b>	<b>D2</b>	<b>D1</b>	<b>D0</b>	<b>3. POWER-DOWN ADC CHANNELS</b>  Power-Down Channels 5 to 8; D3 is for Channel 8 and D0 for Channel 5	
				X	X	X	X		
0	1	0	0	<b>D3</b>	<b>D2</b>	<b>D1</b>	<b>D0</b>	<b>CUSTOM PATTERN (registers 4-6)</b>  Bits for Custom Pattern	
0	1	0	1	MSB	X	X	X		
0	1	1	0	X	X	X	LSB		

TEST PATTERNS(1)	
Deskew	101010101010
Sync	000000111111
Custom	Any 12-bit pattern that is defined in the custom pattern registers 4 to 6. The output comes out in the following order: D0(4) D1(4) D2(4) D3(4) D0(5) D1(5) D2(5) D3(5) D0(6) D1(6) D2(6) D3(6) where, for example, D0(4) refers to the D0 bit of register 4, etc.

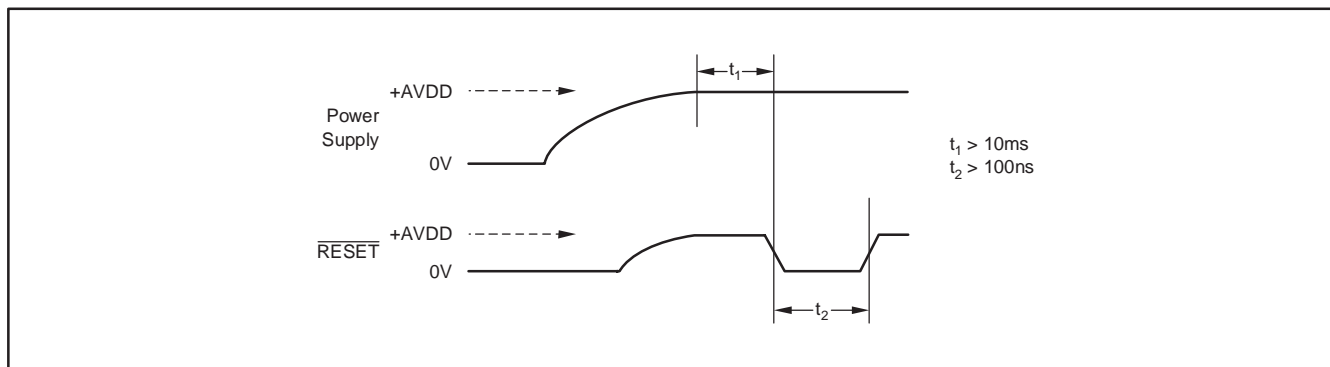
(1) Default is LSB first. If MSB is selected the above patterns will be reversed.

PRODUCT PREVIEW

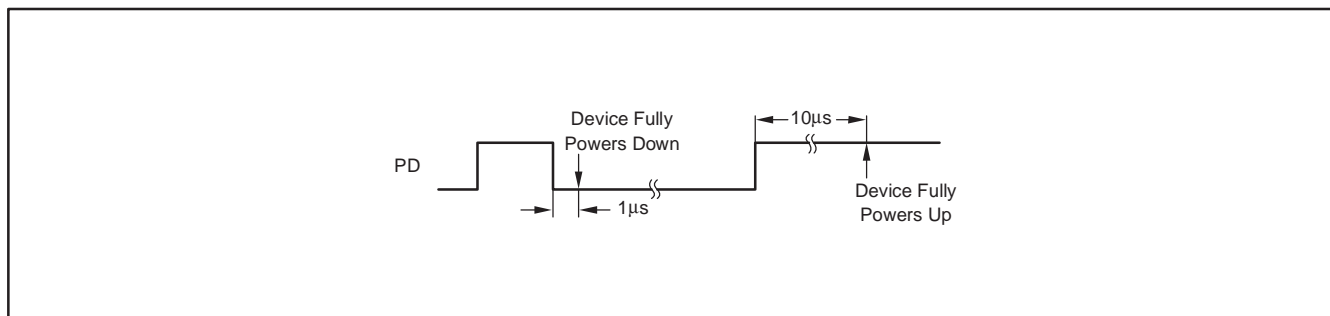
### LVDS TIMING DIAGRAM (PER ADC CHANNEL)



### RESET TIMING

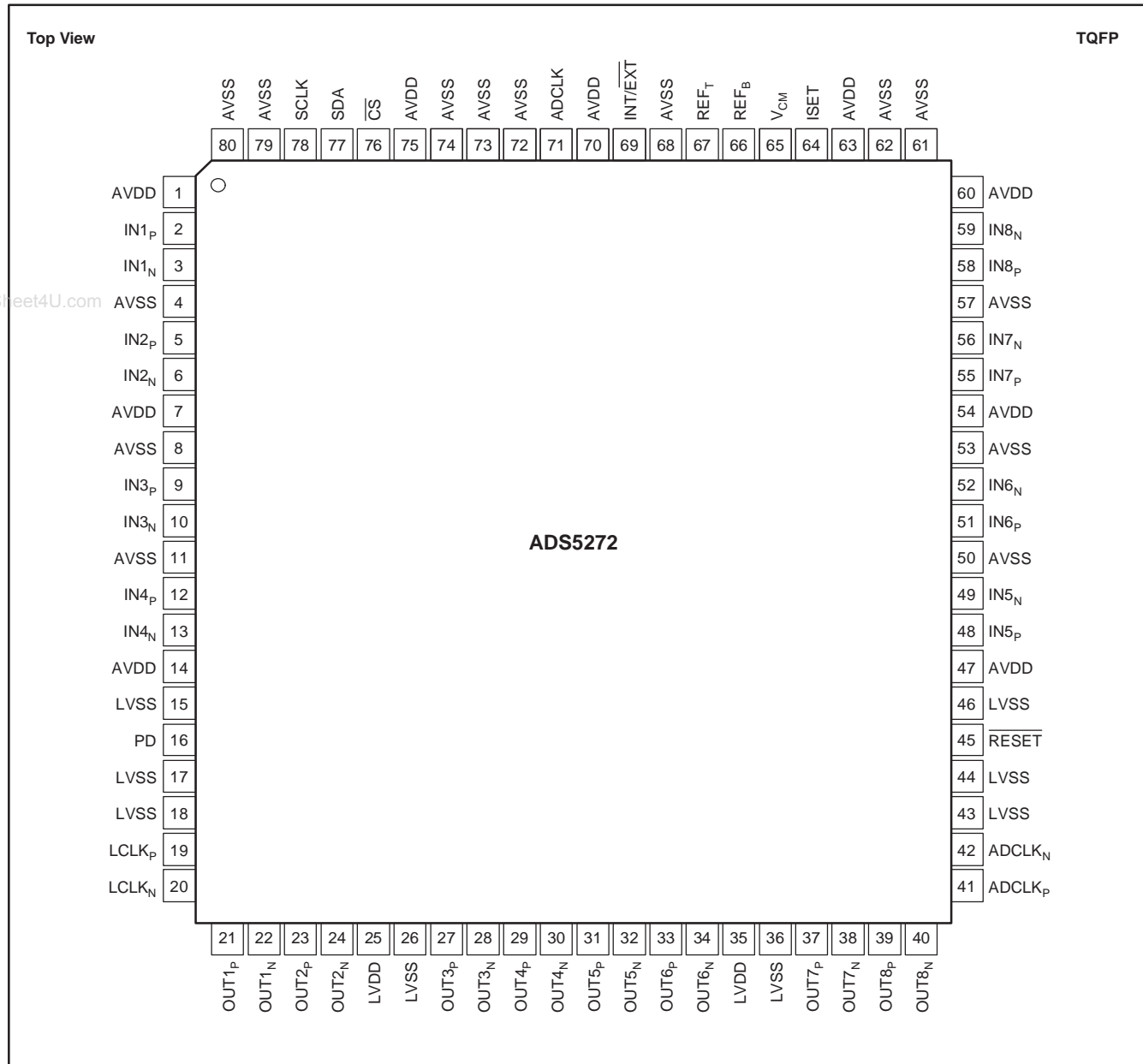


### POWER-DOWN TIMING



PRODUCT PREVIEW

**PIN CONFIGURATION**



**PRODUCT PREVIEW**



**PIN DESCRIPTIONS**

NAME	PIN #	NUMBER OF PINS	I/O	DESCRIPTION
AVDD	1, 7, 14, 47, 54, 60, 63, 70, 75	9	I	Analog Power Supply
AVSS	4, 8, 11, 50, 53, 57, 61, 62, 68, 72-74, 79, 80	14	I	Analog Ground
LVDD	25, 35	2	I	LVDS Power Supply
LVSS	15, 17, 18, 26, 36, 43, 44, 46	8	I	LVDS Ground
IN1P	2	1	I	Channel 1 Differential Analog Input High
IN1N	3	1	I	Channel 1 Differential Analog Input Low
IN2P	5	1	I	Channel 2 Differential Analog Input High
IN2N	6	1	I	Channel 2 Differential Analog Input Low
IN3P	9	1	I	Channel 3 Differential Analog Input High
IN3N	10	1	I	Channel 3 Differential Analog Input Low
IN4P	12	1	I	Channel 4 Differential Analog Input High
IN4N	13	1	I	Channel 4 Differential Analog Input Low
IN5P	48	1	I	Channel 5 Differential Analog Input High
IN5N	49	1	I	Channel 5 Differential Analog Input Low
IN6P	51	1	I	Channel 6 Differential Analog Input High
IN6N	52	1	I	Channel 6 Differential Analog Input Low
IN7P	55	1	I	Channel 7 Differential Analog Input High
IN7N	56	1	I	Channel 7 Differential Analog Input Low
IN8P	58	1	I	Channel 8 Differential Analog Input High
IN8N	59	1	I	Channel 8 Differential Analog Input Low
REF <sub>T</sub>	67	1	I/O	Reference Top Voltage (0.1μF capacitor to ground)
REF <sub>B</sub>	66	1	I/O	Reference Bottom Voltage (0.1μF capacitor to ground)
V <sub>CM</sub>	65	1	O	Common-Mode Output Voltage
INT/EXT	69	1	I	Internal/External Reference Select; 0 = External, 1 = Internal
PD	16	1	I	Power-Down; 0 = Normal, 1 = Power-Down
LCLK <sub>P</sub>	19	1	O	Positive LVDS Clock
LCLK <sub>N</sub>	20	1	O	Negative LVDS Clock
ADCLK	71	1	I	Data Converter Clock Input
OUT1P	21	1	O	Channel 1 Positive LVDS Data Output
OUT1N	22	1	O	Channel 1 Negative LVDS Data Output
OUT2P	23	1	O	Channel 2 Positive LVDS Data Output
OUT2N	24	1	O	Channel 2 Negative LVDS Data Output
OUT3P	27	1	O	Channel 3 Positive LVDS Data Output
OUT3N	28	1	O	Channel 3 Negative LVDS Data Output
OUT4P	29	1	O	Channel 4 Positive LVDS Data Output
OUT4N	30	1	O	Channel 4 Negative LVDS Data Output
OUT5P	31	1	O	Channel 5 Positive LVDS Data Output
OUT5N	32	1	O	Channel 5 Negative LVDS Data Output
OUT6P	33	1	O	Channel 6 Positive LVDS Data Output
OUT6N	34	1	O	Channel 6 Negative LVDS Data Output
OUT7P	37	1	O	Channel 7 Positive LVDS Data Output
OUT7N	38	1	O	Channel 7 Negative LVDS Data Output
OUT8P	39	1	O	Channel 8 Positive LVDS Data Output
OUT8N	40	1	O	Channel 8 Negative LVDS Data Output
ADCLK <sub>P</sub>	41	1	O	Positive LVDS ADC Clock Output
ADCLK <sub>N</sub>	42	1	O	Negative LVDS ADC Clock Output
ISET	64	1	I/O	Bias Current Setting Resistor of 56kΩ to Ground
RESET	45	1	I	Reset to Default; 0 = Reset, 1 = Normal
$\overline{\text{CS}}$	76	1	I	Chip Select; 0 = Select, 1 = No Select
SDA	77	1	I	Serial Data Input
SCLK	78	1	I	Serial Data Clock

## THEORY OF OPERATION

### OVERVIEW

The ADS5272 is an 8-channel, high-speed, CMOS ADC. It consists of a high-performance sample-and-hold circuit at the input, followed by a 12-bit ADC. The 12 bits given out by each channel are serialized and sent out on a single pair of pins in LVDS format. All eight channels of the ADS5272 operate from a single clock referred to as ADCLK. The sampling clocks for each of the eight channels are generated from the input clock using a carefully matched clock buffer tree. The 12X clock required for the serializer is generated internally from ADCLK using a phase lock loop (PLL). A 6X and a 1X clock are also output in LVDS format along with the data to enable easy data capture. The ADS5272 operates from internally generated reference voltages that are trimmed to ensure matching across multiple devices on a board. This feature eliminates the need for external routing of reference lines and also improves matching of the gain across devices. The nominal values of  $REF_T$  and  $REF_B$  are 2V and 1V, respectively. These values imply that a differential input of  $-1V$  corresponds to the zero code of the ADC, and a differential input of  $+1V$  corresponds to the full-scale code (4095 LSB).  $V_{CM}$  (common-mode voltage of  $REF_P$  and  $REF_N$ ) is also made available externally through a pin, and is nominally 1.5V.

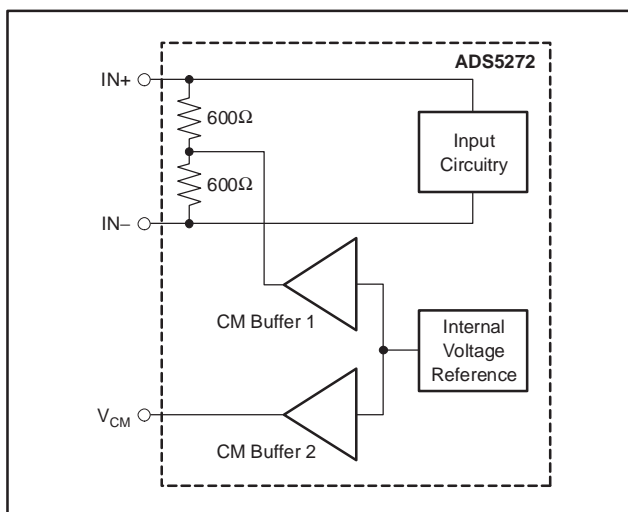
The ADC employs a pipelined converter architecture consisting of a combination of multi-bit and single-bit internal stages. Each stage feeds its data into the digital error correction logic, ensuring excellent differential linearity and no missing codes at the 12-bit level. The pipeline architecture results in a data latency of 6.5 clock cycles.

The output of the ADC goes to a serializer that operates from a 12X clock generated by the PLL. The 12 data bits from each channel are serialized and sent LSB first. In addition to serializing the data, the serializer also generates a 1X clock and a 6X clock. These clocks are generated in the same way the serialized data is generated, so these clocks maintain perfect synchronization with the data. The data and clock outputs of the serializer are buffered externally using LVDS buffers. Using LVDS buffers to transmit data externally has multiple advantages, such as reduced number of output pins (saving routing space on the board), reduced power consumption, and reduced effects of digital noise coupling to the analog circuit inside the ADS5272.

The ADS5272 operates from two sets of supplies and grounds. The analog supply/ground set is denoted as AVDD/AVSS, while the digital set is denoted by LVDD/LVSS.

### DRIVING THE ANALOG INPUTS

The analog input biasing is shown in Figure 1. The recommended method to drive the inputs is through AC coupling. AC coupling removes the worry of setting the common-mode of the driving circuit, since the inputs are biased internally using two  $600\Omega$  resistors.



**Figure 1. Analog Input Bias Circuitry**

The sampling capacitor used to sample the inputs is 4pF. The choice of the external AC coupling capacitor is dictated by the attenuation at the lowest desired input frequency of operation. The attenuation resulting from using a 10nF AC coupling capacitor is 0.04%.

If the input is DC-coupled, then the output common-mode voltage of the circuit driving the ADS5272 should match the  $V_{CM}$  (which is provided as an output pin) to within  $\pm 50mV$ . It is recommended that the output common-mode of the driving circuit be derived from  $V_{CM}$  provided by the device.

The sampling circuit consists of a low-pass RC filter at the input to filter out noise components that might be getting differentially coupled on the input pins. The inputs are sampled on two 4pF capacitors as shown in Figure 2. The sampling on the capacitors is done with respect to an internally generated common-mode voltage (INCM). The switches connecting the sampling capacitors to the INCM are opened out first (before the switches connecting them to the analog inputs). This ensures that the charge injection arising out of the switches opening is independent of the input signal amplitude to a first-order of approximation. SP refers to a sampling clock whose falling edge comes an instant before the SAMPLE clock. The falling edge of SP determines the sampling instant.

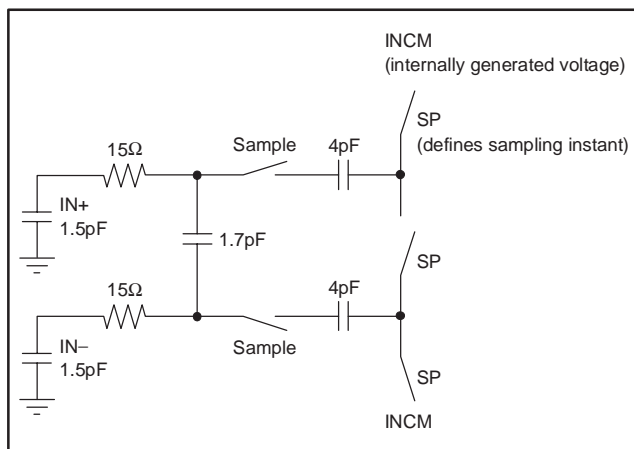


Figure 2. Input Circuitry

### INPUT OVER-VOLTAGE RECOVERY

The differential full-scale input peak-to-peak supported by the ADS5272 is 2V. For a nominal value of  $V_{CM}$  (1.5V),  $IN_P$  and  $IN_N$  can swing from 1V to 2V. The ADS5272 is specially designed to handle an over-voltage differential peak-to-peak voltage of 4V (2.5V and 0.5V swings on  $IN_P$  and  $IN_N$ ). If the input common-mode is not considerably off from  $V_{CM}$  during overload (less than 300mV), recovery from an over-voltage input condition is expected to be within 4 clock cycles. All of the amplifiers in the SHA and ADC are specially designed for excellent recovery from an overload signal.

### REFERENCE CIRCUIT DESIGN

The digital beam-forming algorithm relies heavily on gain matching across all receiver channels. A typical system would have about 12 octal ADCs on the board. In such a case, it is critical to ensure that the gain is matched, essentially requiring the reference voltages seen by all the ADCs to be the same. Matching references within the eight channels of a chip is done by using a single internal reference voltage buffer. Trimming the reference voltages on each chip during production ensures the reference voltages are well matched across different chips.

All bias currents required for the internal operation of the device are set using an external resistor to ground at pin ISET. Using a 56kΩ resistor on ISET generates an internal reference current of 20μA. This current is mirrored internally to generate the bias current for the internal blocks. Using a larger external resistor at ISET reduces the reference bias current and thereby scales down the device operating power. However, it is recommended that the external resistor be within 10% of the specified value of 56k so that the internal bias margins for the various blocks are proper.

Buffering the internal bandgap voltage also generates a voltage called  $V_{CM}$ , which is set to the midlevel of  $REF_T$  and  $REF_B$ , and is accessible on a pin. The internal buffer driving  $V_{CM}$  has a drive of ±2mA. It is meant as a reference voltage to derive the input common-mode in case the input is directly coupled.

When using the internal reference mode, a resistor greater than 2Ω should be added between the reference pins ( $REF_T$  and  $REF_B$ ) and the decoupling capacitor, as shown in Figure 3.

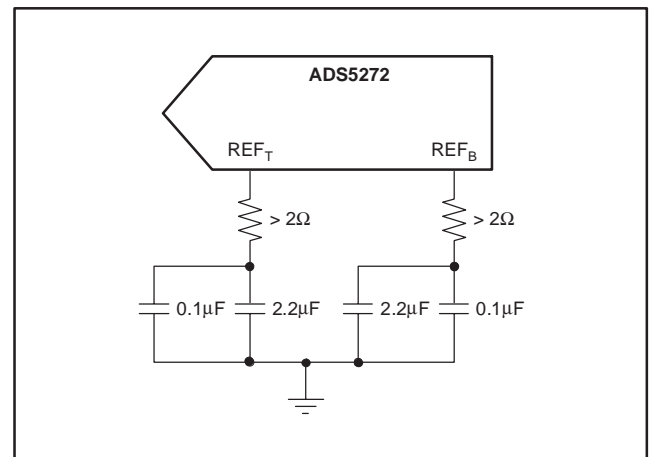


Figure 3. Internal Reference Mode

The device also supports the use of external reference voltages. This mode involves forcing  $REF_T$  and  $REF_B$  externally. In this mode, the internal reference buffer is tri-stated. Since the switching current for the eight ADCs come from the externally forced references, it is possible for the performance to be slightly less than when the internal references are used. It should be noted that in this mode,  $V_{CM}$  and ISET continue to be generated from the internal bandgap voltage, as in the internal reference mode. It is therefore important to ensure that the common-mode voltage of the externally forced reference voltages matches to within 50mV of  $V_{CM}$ .

### CLOCKING

The eight channels on the chip run off a single ADCLK input. To ensure that the aperture delay and jitter are same for all the channels, a clock tree network is used to generate individual sampling clocks to each channel. The

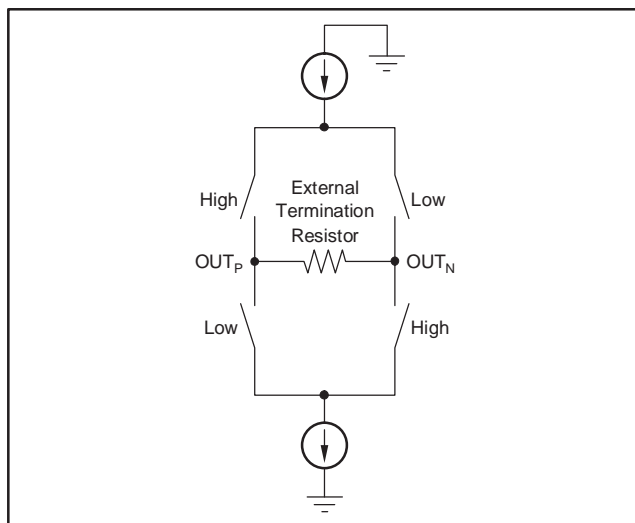
clock paths for all the channels are matched from the source point all the way to the sample-and-hold. This ensures that the performance and timing for all the channels are identical. The use of the clock tree for matching introduces an aperture delay, which is defined as the delay between the rising edge of ADCLK and the actual instant of sampling. The aperture delays for all the channels are matched, and vary between 2.5ns to 4.5ns across devices. Another critical spec is the aperture jitter that is defined as the uncertainty of the sampling instant. The gates in the clock path are designed so as to give an rms jitter of about 1ps.

The input ADCLK should ideally have a 50% duty cycle. However, while routing ADCLK to different components on board, the duty cycle of the ADCLK reaching the ADS5272 could deviate from 50%. A smaller (or larger) duty cycle eats into the time available for sample or hold phases of each circuit, and is therefore not optimal. For this reason, the internal PLL is used to generate an internal clock that has 50% duty cycle.

The use of the PLL automatically dictates the lower frequency of operation to be about 20MHz.

## LVDS BUFFERS

The LVDS buffer has two current sources, as shown in Figure 4.  $OUT_P$  and  $OUT_N$  are loaded externally by a resistive load that is ideally about  $100\Omega$ . Depending on the data being 0 or 1, the currents are directed in one or the other direction through the resistor. The LVDS buffer has four current settings. The default current setting is 3.5mA, and gives a differential drop of about  $\pm 350mV$  across the  $100\Omega$  resistor.



**Figure 4. LVDS Buffer**

The LVDS buffer gets data from a serializer that takes the output data from each channel and serializes it into a single data stream. For a clock frequency of 40MHz, the

data rate output by the serializer is 480 MBPS. The data comes out LSB first, with a register programmability to revert to MSB first. The serializer also gives out a 1X clock and a 6X clock. The 6X clock (denoted as  $LCLK_P/LCLK_N$ ) is meant to synchronize the capture of the LVDS data. The deskew mode can be enabled as well, using a register setting. This mode gives out a data stream of alternate 0s and 1s and can be used to determine the relative delay between the 6X clock and the output data for optimum capture. A 1X clock is also generated by the serializer and transmitted by the LVDS buffer. The 1X clock (referred to as  $ADCLK_P/ADCLK_N$ ) is used to determine the start of the 12-bit data frame. The sync mode (enabled through a register setting) gives out a data of six 0s followed by six 1s. Using this mode, the 1X clock can be used to determine the start of the data frame. In addition to the deskew mode pattern and the sync pattern, a custom pattern can be defined by the user and output from the LVDS buffer.

## NOISE COUPLING ISSUES

High-speed mixed signals are sensitive to various types of noise coupling. One of the main sources of noise is the switching noise from the serializer and the output buffers. Maximum care is taken to isolate these noise sources from the sensitive analog blocks. As a starting point, the analog and digital domains of the chip are clearly demarcated. AVDD and AVSS are used to denote the supplies for the analog sections, while LVDD and LVSS are used to denote the digital supplies. Care is taken to ensure that there is minimal interaction between the supply sets within the device. The extent of noise coupled and transmitted from the digital to the analog sections depends on the following:

1. The effective inductances of each of the supply/ground sets.
2. The isolation between the digital and analog supply/ground sets.

Smaller effective inductance of the supply/ground pins leads to better suppression of the noise. For this reason, multiple pins are used to drive each supply/ground. It is also critical to ensure that the impedances of the supply and ground lines on board are kept to the minimum possible values. Use of ground planes in the board as well as large decoupling capacitors between the supply and ground lines are necessary to get the best possible SNR from the device.

It is recommended that the isolation be maintained on board by using separate supplies to drive AVDD and LVDD, as well as separate ground planes for AVSS and LVSS.

The use of LVDS buffers reduces the injected noise considerably, compared to CMOS buffers. The current in the LVDS buffer is independent of the direction of switching. Also, the low output swing as well as the differential nature of the LVDS buffer results in low-noise coupling.

## POWER-DOWN MODE

The ADS5272 has a power-down pin, PD. Pulling PD high causes the devices to enter the power-down mode. In this mode, the reference and clock circuitry as well as all the channels are powered down. Device power consumption drops to less than 100mW in this mode. Individual channels can also be selectively powered down by programming registers.

The ADS5272 also has an internal circuit that monitors the state of stopped clocks. If ADCLK is stopped (or if it runs at a speed < 3MHz), this monitoring circuit generates a logic signal that puts the device in a power-down state. As a result, the power consumption of the device goes to less than 100mW when ADCLK is stopped. This circuit can also be disabled using register options.

## SUPPLY SEQUENCE

The following supply sequence is recommended for powering up the device:

1. AVDD is powered up.
2. LVDD is powered up.

After the supplies have stabilized, it is required to give the device an active RESET pulse. This results in all internal registers getting reset to their default value of 0 (inactive). Without RESET, it is possible that some registers might be in their non-default state on power-up. This could cause the device to malfunction.

## LAYOUT OF PCB WITH PowerPAD THERMALLY- ENHANCED PACKAGES

The ADS5272 is housed in an 80-lead PowerPAD thermally-enhanced package. To make optimum use of the thermal efficiencies designed into the PowerPAD package, the PCB must be designed with this technology in mind. Please refer to SLMA004 PowerPAD brief *PowerPAD Made Easy* (refer to our web site at [www.ti.com](http://www.ti.com)), which addresses the specific considerations required when integrating a PowerPAD package into a PCB design. For more detailed information, including thermal modeling and repair procedures, please see SLMA002 technical brief *PowerPAD Thermally Enhanced Package* ([www.ti.com](http://www.ti.com)).

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
ADS5272IPFP	PREVIEW	HTQFP	PFP	80	96	TBD	Call TI	Call TI
ADS5272IPFPT	PREVIEW	HTQFP	PFP	80		TBD	Call TI	Call TI

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

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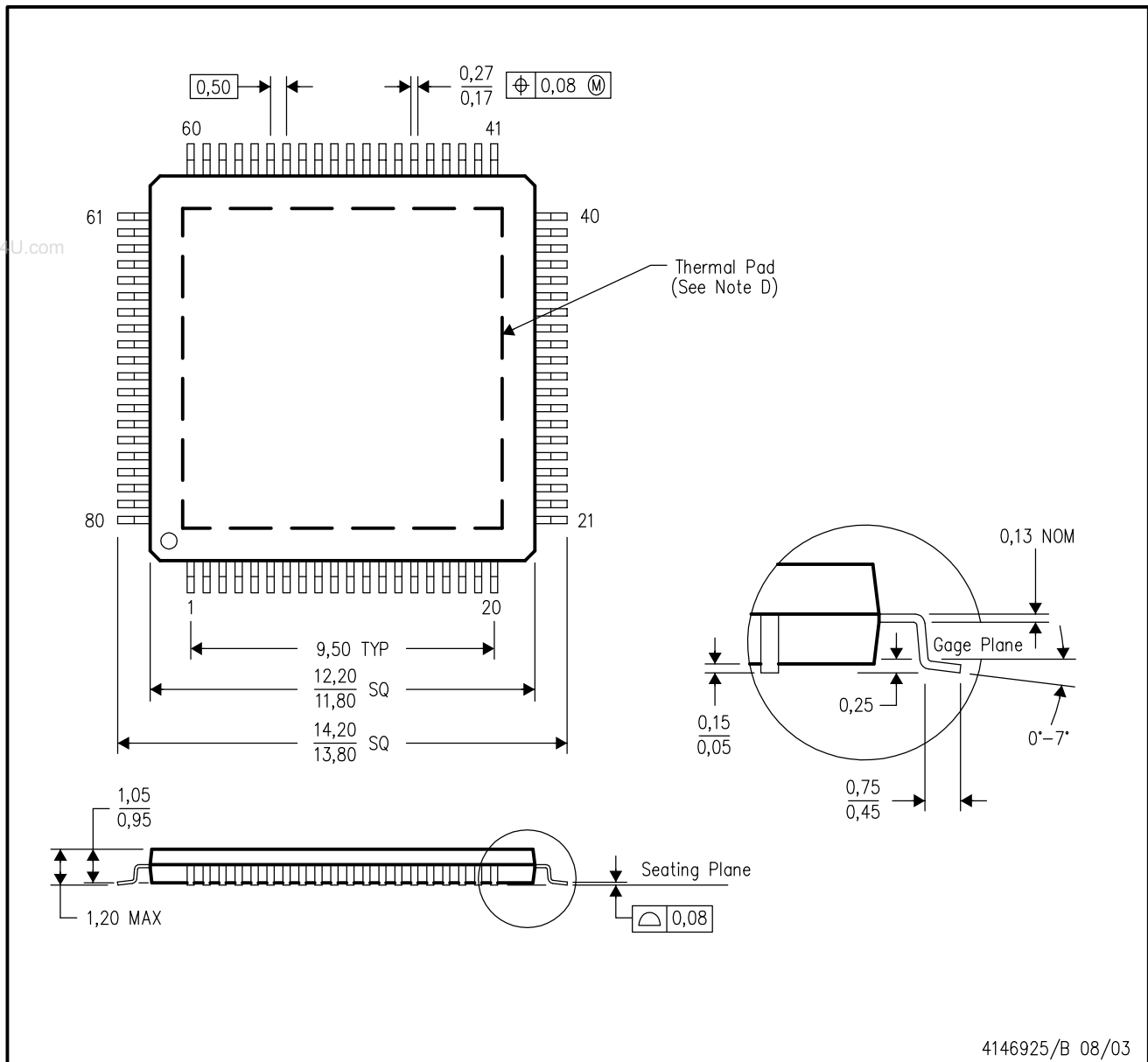
<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion
  - D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at [www.ti.com](http://www.ti.com) <<http://www.ti.com>>.
  - E. Falls within JEDEC MS-026

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